

# ALUNABEADS CB SERIES

## Typical properties of common grades

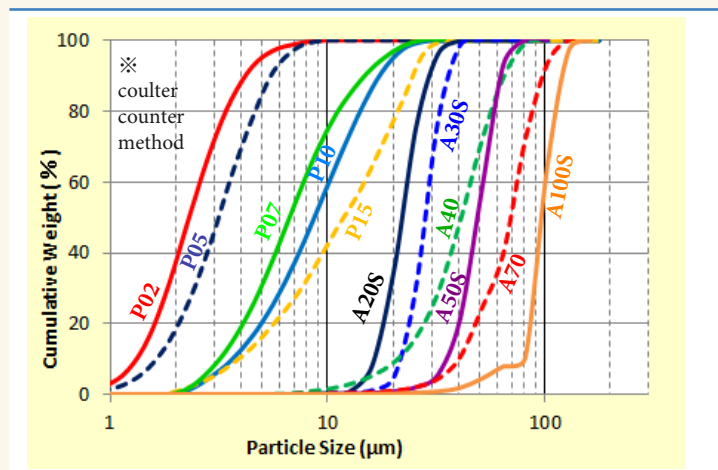
		CB -P02	CB -P05	CB -P07 <sup>※</sup>	CB -P10	CB -P15	CB -A20S	CB -A30S	CB -A40	CB -A50S	CB -A70	CB -A100S	
Chemical Composition	L.O.I. <sup>※1</sup>	%	0.07	0.05	0.05	0.05	0.04	0.03	0.03	0.04	0.02	0.02	0.03
	Fe <sub>2</sub> O <sub>3</sub>	%	0.01	0.02	0.01	0.01	0.02	0.01	0.01	0.02	0.01	0.02	0.01
	SiO <sub>2</sub>	%	0.04	0.02	0.02	0.01	0.06	0.02	0.01	0.01	0.04	0.01	0.04
	Na <sub>2</sub> O	%	0.04	0.03	0.14	0.26	0.06	0.03	0.01	0.02	0.01	0.06	0.00
	Na <sup>+</sup> <sup>※2</sup>	ppm	8	5	23	22	6	10	8	21	6	30	8
	Al <sub>2</sub> O <sub>3</sub>	%	99.88	99.91	99.79	99.69	99.82	99.91	99.94	99.92	99.92	99.89	99.92
Mean Particle Size (d <sub>50</sub> ) <sup>※3</sup>		μm	3	4	7	8	16	21	28	46	50	71	97
Top cut size		μm	24	24	45	24	45	45	45	88	88	149	149
BET Specific Surface area		m <sup>2</sup> /g	1.1	0.6	0.4	0.5	0.3	0.2	0.2	0.2	0.1	0.1	0.1
Bulk Density	Loose	g/cm <sup>3</sup>	0.9	1.2	1.4	1.4	1.7	2.1	2.1	2.1	2.1	2.1	2.2
	Tap	g/cm <sup>3</sup>	2.0	2.2	2.5	2.4	2.5	2.3	2.3	2.4	2.3	2.4	2.4
Electric Conductivity <sup>※4</sup>		μS/cm	12	17	20	23	8	7	6	17	4	24	5
Viscosity (Pas)	Epoxy resin (250PHR)		142	130	-	85	76	116	117	138	99	105	-
	Silicone resin (600PHR)		305	274	-	123	73	104	90	100	77	57	-

※1 Loss On Ignition, ※2 Warm water extraction (100°C, 2Hr), ※3 LASER DIFFRACTION AND SCATTERING METHOD ANALYZER

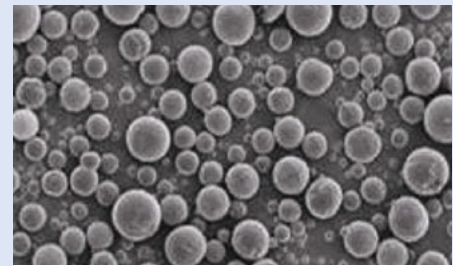
※4 20g/100ml purified water, ※The data shown above are representative figures. They are not guaranteed values.

※ CB-P07 is development product.

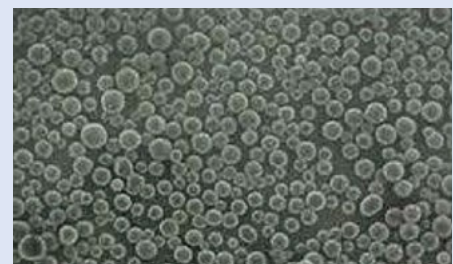
### Particle Size Distribution



### SEM images



CB-A40



CB-A20S

### Features and Advantages

- Spherical shape allows for especially high filling into resin. It is especially suitable for applications which require high fluidity.
- CB-A20S and CB-A50S grades have a sharp particle size distribution, while CB-A40, CB-A70, and CB-P02 grades have a broad particle size distribution.
- Alunabeads CB Series has good properties for special abrasives in addition to insulation and thermal filler applications.